

## Description

The IRF8714PBF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =15 A

 $R_{DS(ON)} < 9m\Omega$  @ V<sub>GS</sub>=10V

 $R_{DS(ON)} < 14m\Omega$  @ V<sub>GS</sub>=4.5V

## Application

Battery protection

Load switch

Uninterruptible power supply

#### Package Marking and Ordering Information

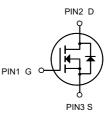
Product ID	Pack	Brand	Qty(PCS)
IRF8714PBF	SOP-8	HXY MOSFET	3000

# Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current-Continuous	15.0	А
l₀(70 °C)	Drain Current-Continuous(Tc=70℃)	8.2	A
DM	Pulsed Drain Current	42	А
PD	Maximum Power Dissipation	1.5	W
Eas	Single pulse avalanche energy (Note 5)	62	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C
Rejc	Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	36	°C <b>/W</b>



SOP-8



N-Channel MOSFET



N-Channel Enhancement Mode MO	OSFET
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Symbol	nbol Parameter Conditions		Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25°C,I⊳=1mA		0.027		V/°C	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =10A		7.5	9	mΩ	
	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A		11	14		
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2	1.5	2.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	──V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-5.8		mV/°C	
	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C				uA	
lgss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		5.8		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.2	3.8	Ω	
Qg	Total Gate Charge (4.5V)			12.6	17.6		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		4.2	5.9	nC	
$Q_{gd}$	Gate-Drain Charge			5.1	7.1		
T <sub>d(on)</sub>	Turn-On Delay Time			6.2	12.4		
Tr	Rise Time			59	106	ns	
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =10A		27.6	55		
Tf	Fall Time			8.4	16.8		
Ciss	Input Capacitance			1317	1845		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		163	228.2	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			131	183.4		
ls	Continuous Source Current <sup>1,5</sup>				10.3	Α	
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	──V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			42	A	
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V	
trr	Reverse Recovery Time			12.5		nS	
Qrr	Reverse Recovery Charge	IF=10A , dl/dt=100A/µs , Tյ=25°C		5		nC	

# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Note :

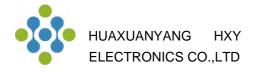
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =35A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.





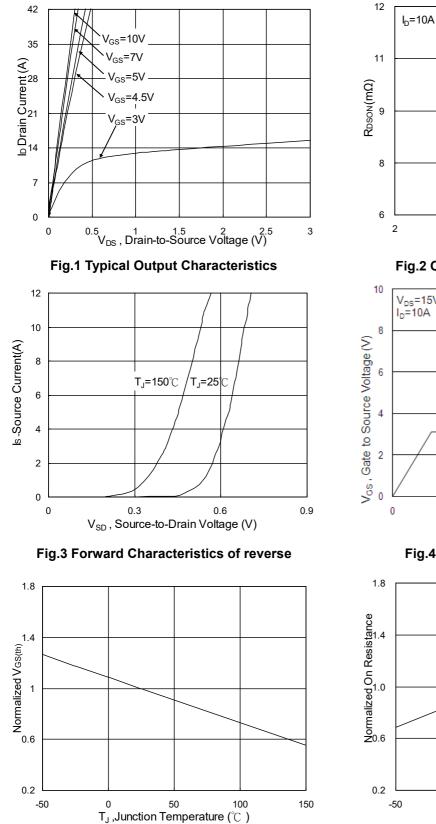
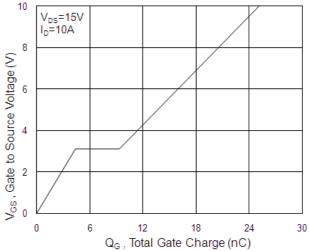


Fig.2 On-Resistance vs. Gate-Source

4



6 V<sub>GS</sub> (V)

8

10

Fig.4 Gate-Charge Characteristics

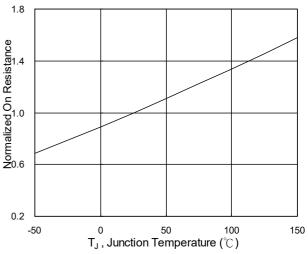
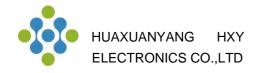


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>



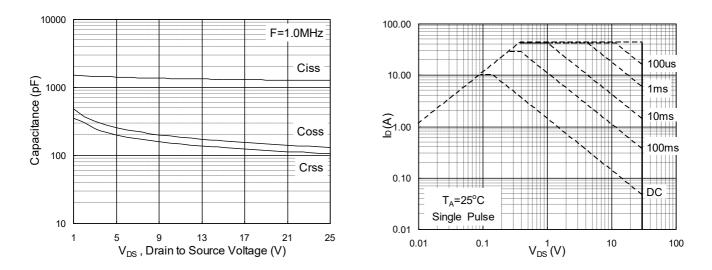
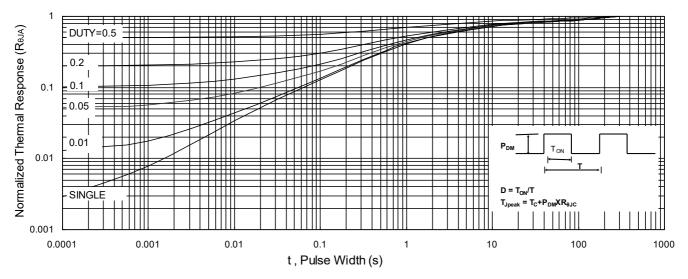


Fig.7 Capacitance

Fig.8 Safe Operating Area





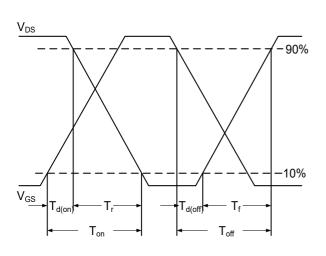


Fig.10 Switching Time Waveform

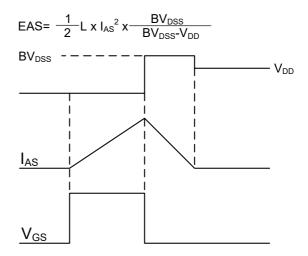
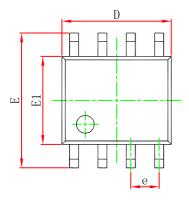
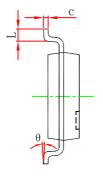


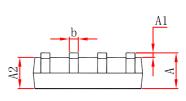
Fig.11 Unclamped Inductive Switching Waveform



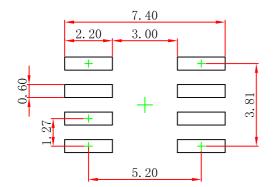
# SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
Α	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
с	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0 °	8°	0 °	8°



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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